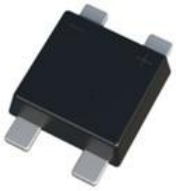
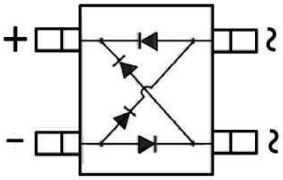
0.8A Glass Passivated Bridge Rectifier

Features

- Glass Passivated Chip Junction
- Low Reverse Voltage Leakage Current
- High Surge Current Capability
- Low Forward Voltage Drop
- Reverse Voltage : 50 to 1000V
- Forward Current : 0.8A
- High temperature soldering : 260°C/10s at terminals



UMBF



Applications

- Switching power supply

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter		Symbol	UMB 05F	UMB 1F	UMB 2F	UMB 4F	UMB 6F	UMB 8F	UMB 10F	Unit
Maximum Repetitive Peak Reverse Voltage		V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage		V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage		V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current@T_C=115℃		$I_{F(AV)}$	0.8							A
Peak Forward Surge Current 8.3mS single half sine wave superimposed on rated load (JEDEC method)		I_{FSM}	25							A
Maximum Instantaneous Forward Voltage @0.8A		V_F	1.1							V
Maximum DC Reverse Current at Rated DC Blocking Voltage	T_A=25℃	I_R	5.0							μA
	T_A=125℃		100							
Typical Junction Capacitance (Note 1)		C_J	13							pF
Typical Thermal Resistance (Note 2)		$R_{\theta JA}$	110							°C/ W
Operating Junction and Storage Temperature Range		T_J, T_{STG}	(-55 to+150)							°C

Notes:

1. Measured at 1.0MHz and applied reverse voltage of 4.0 Volts.
2. P.C.B. mounted with 4×1.5"×1.5" (3.81×3.81 cm) copper pad areas.

Ratings and Characteristic Curves (T_A=25℃ unless otherwise noted)

Fig.1 Average Rectified Output Current Derating Curve

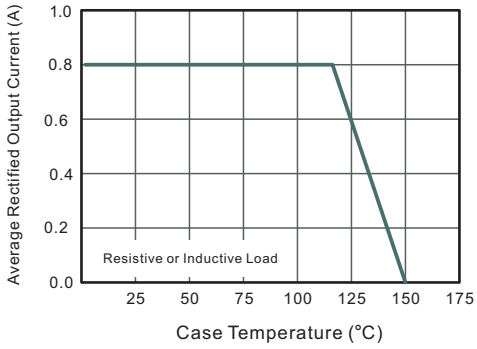


Fig.2 Typical Reverse Characteristics

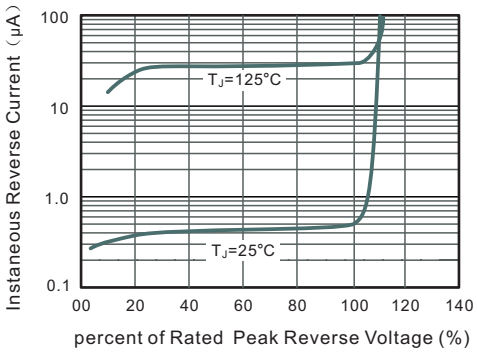


Fig.3 Typical Instaneous Forward Characteristics

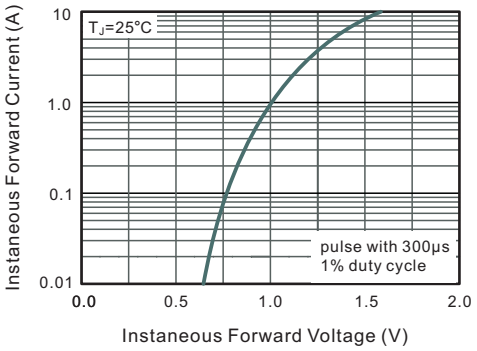


Fig.4 Typical Junction Capacitance

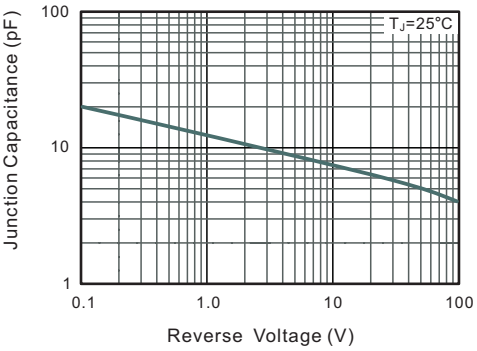
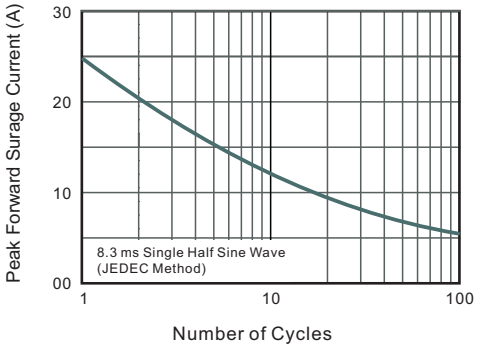
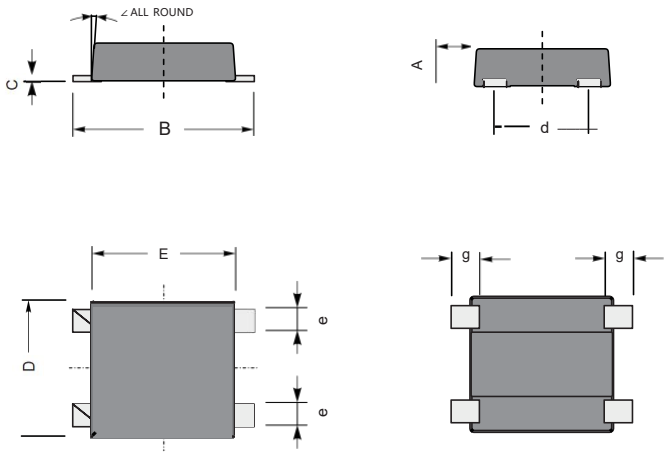


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current



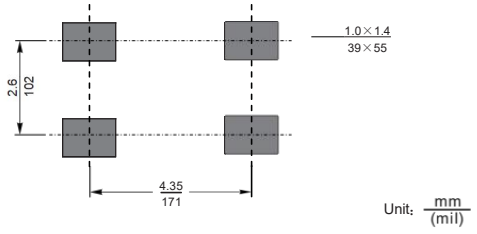
Package Outlines (Dimensions in mm)

Plastic surface mounted package(UMBF)



UNIT		A	C	D	E	B	g	d	e
mm	max	1.4	0.3	4.05	3.9	5.2	0.95	2.8	0.9
	min	1.0	0.1	3.65	3.5	4.8	0.55	2.4	0.5

The recommended mounting pad size



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